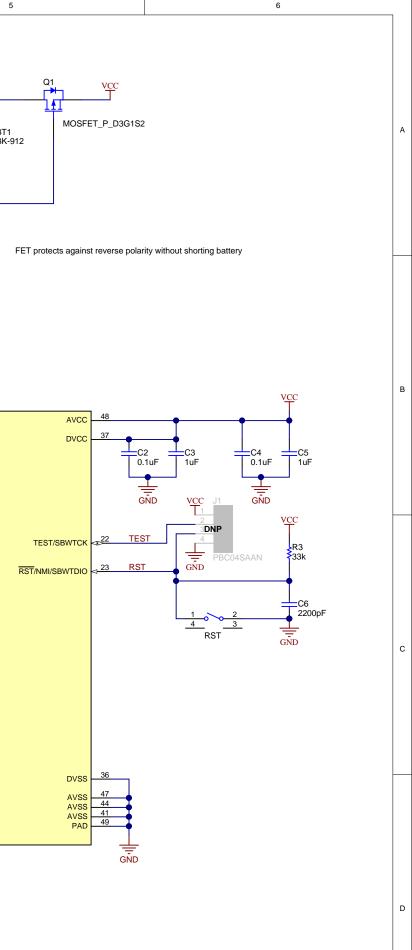
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A	VCC	U1 5			BT1 BK-912 GND FET protects against rever	-	
В	GND	SCL GND Z ALERT PAD Z TMP116 GND	TP4 GN	TP1 -2m> P1.1/TA0.2/TA1C R1 R2 -3m> P1.2/TA1.1/TA0C 10k 10k -0m> P1.3/TA1.2/UCB0 10k 10k -0m> P1.3/TB0.2/UCA0 10m -0m> P1.3/TB0.2/UCA0	E0/RTCCLK/A0/C0/VREF-/VeREF- 2LK/COUT/A1/C1/VREF+/VeREF+ 2LK/COUT/A2/C2 DVCC 37 JSTE/A3/C3	$\begin{array}{c} VCC \\ \hline C2 \\ 0.1 uF \\ \hline UF \\ \hline C3 \\ \hline 0.1 uF \\ \hline UF \hline \hline UF \\ \hline UF \\ \hline UF \\ \hline UF \hline \hline UF \\ \hline UF \hline \hline UF \\ \hline UF \hline \hline UF$	
с		128x128 LCD_Module_128x128 J2 1 SPI_CLK 0 2 SPI_SI 0 3 SPI_CS 0 4 0 5 DISP 0 6 0 7 0 8 0 9 0 10	VCC C7 0.1uF		ISTE/A6/C10 ICLK/A7/C11 ITXD/UCA1SIMO IRXD/UCA1SOMI IRXD/UCA1SOMI IRXD/UCA1SOMI IRXD/UCA1SOMI	TEST THE PBC04SAAN \$33k	pF
D		GND	GND UNE.00M		JTH/SMCLK/SRSCG1/C6 ICLK/SRSCG0/C7 SROSCOFF/C8 JOFF/C9 AVSS 47 AVSS 44 AVSS 44 PAD IRGZ		
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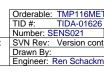
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ZZ1 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

1

ZZ2 Assembly Note These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



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